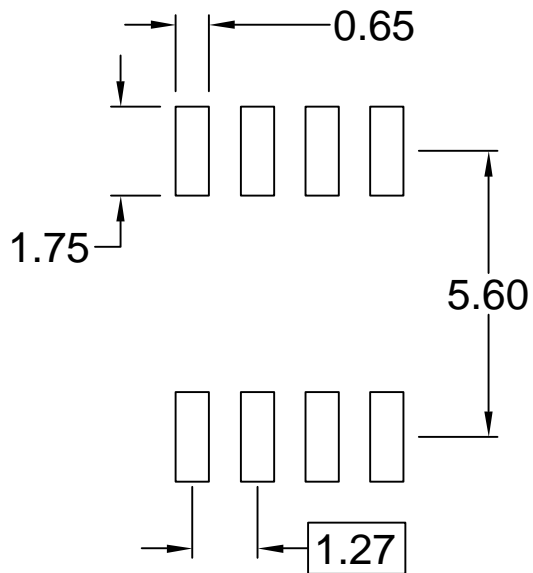
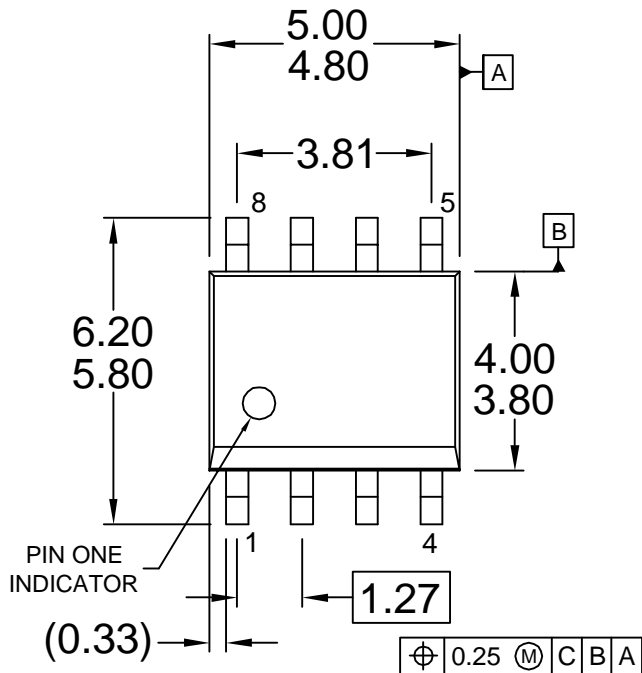
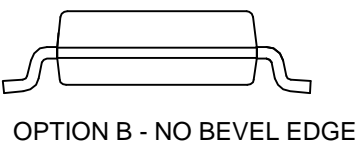
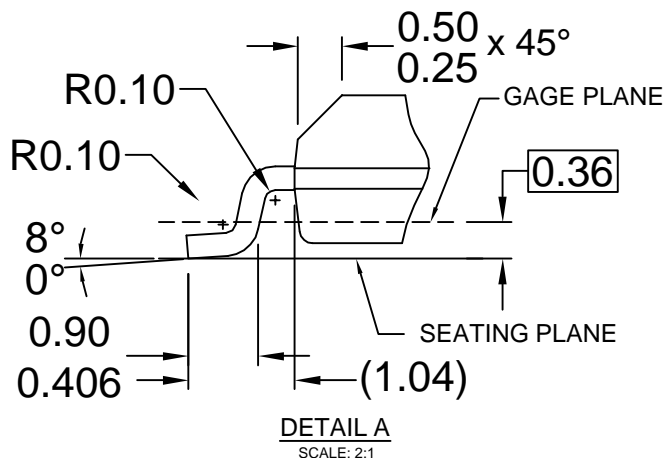
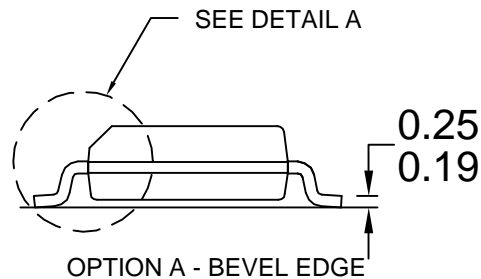
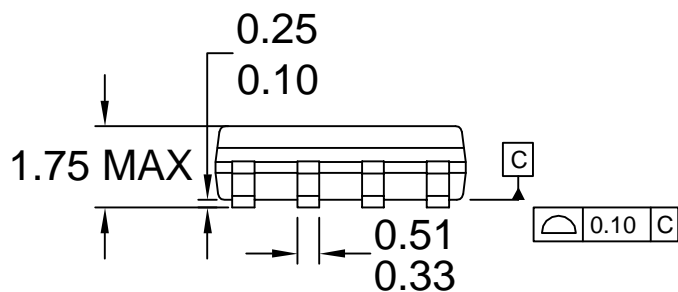


| REVISIONS |  |            |            |
|-----------|--|------------|------------|
| LTR       | DESCRIPTION  | DATE       | BY/APP'D   |
| 12        | CHANGED LEADSPREAD, TERMINAL WIDTH, AND FOOT LENGTH, REMOVED REFERENCE TO LEAD FINISH. | 27 JULY 07 | L.HUEBENER |
| 13        | ADDED OPTION "A" AND "B" VIEW  | 19 SEPT 07 | H.ALLEN    |



LAND PATTERN RECOMMENDATION



NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AA, ISSUE C,
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X175-8M.
- E) DRAWING FILENAME: M08AREV13

| APPROVALS            | DATE       | FAIRCHILD SEMICONDUCTOR                        |      |                |        |
|----------------------|------------|--|------|----------------|--------|
| DRAWN: H.ALLEN       | 19 SEPT 07 | 8LD, SOIC, JEDEC MS-012,<br>0.150" NARROW BODY |      |                |        |
| DFTG. CHK: SSI. CHOI | 20 SEPT 07 |  |      |                |        |
| ENGR. CHK:           |            |  |      |                |        |
| PROJECTION           |            | SCALE  | SIZE | DRAWING NUMBER | REV    |
|                      |            | N/A  | C    | MKT-M08A       | 13     |
|                      |            | DO NOT SCALE DRAWING                           |      | SHEET          | 1 of 1 |